













ESD

178

TSS

MOV

GDT

PLED

SMF5.0A- SMF170CA

# **Product specification**





VOLTAGE RANGE: 8 .0 V POWER: 200Wa tts

### Features

- For surface mounted applications
- Low profile package
- Low incremental surge resistance, excellent
- clamping capability
- 200W peak pulse power capability with a10/1000 µs wave from,repetition rate (dutycycle):0.01%
- High temperature soldering guaranteed: 260 ℃/10 seconds, at terminals

# Mechanical Data

- Case: JEDEC SOD- 123FL, molded plastic over passivated chip
- Polarity: Color band denotes positiveend( cathode ) except for bidirectional
- Mounting position: Any
- Weight: 0.006 ounces, 0.02 gram

## **Reference News**



# Maximum Ratings TA = $25^{\circ}$ C unless otherwise specified

Characteristic	Symbol	Value	Unit
Maximum P <sub>PK</sub> Dissipation (PW -10/1000μs)	Р <sub>РК</sub>	200	W
Maximum $P_{PK}$ Dissipation @Ta =25 °C (PW - 8/10µs) (Note2)	Ррк	1000	W
DC Power Dissipation @Ta= 25°C (Note 3)	PD	385	W
Derate above 25 ℃		4.0	mW/ °C
Thermal Resistance, Junction to Ambient (Note3)	R <sub>0 JA</sub>	325	°C /W
Thermal Resistance, Junction to Lead (Note 3)	R <sub>0 JL</sub>	26	°C /W
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to + 150	٦°

#### Notes :

(1) Non-repetitive current pulse at Ta = 25°C, per waveform of Fig. 2.

- (2) Non-repetitive current pulse at Ta = 25°C, per waveform of Fig.5.
- (3) Mounted with recommended minimum pad size, DC board FR4.



ТҮРЕ		Marking		Reverse Stand- Off Voltage	Breakdow n Voltage Min. @I⊤	Breakdow n Voltage Max.@ Ιτ	Test Current	Reverse Leakage @V <sub>RWM</sub>	Maximum Clamping Voltage @ Ipp	Peak
(Uni)	(Bi)	(Uni)	(Bi)	Vrwm (V)	VBR MIN(V)	VBR MAX(V)	Iт (mA)	l <sub>R</sub> (uA)	Vc(V)	IPP (A)
SMF5.0A	SMF5.0CA	KE	FE	5.0	6.40	7.00	10	400	9.2	21.7
SMF6.0A	SMF6.0CA	KG	FG	6.0	6.67	7.37	10	400	10.3	19.4
SMF6.5A	SMF6.5CA	KK	FK	6.5	7.22	7.98	10	250	11.2	17.9
SMF7.0A	SMF7.0CA	KM	FM	7.0	7.78	8.60	10	100	12.0	16.7
SMF7.5A	SMF7.5CA	KP	FP	7.5	8.33	9.21	1.0	50	12.9	15.5
SMF8.0A	SMF8.0CA	KR	FR	8.0	8.89	9.83	1.0	25	13.6	14.7
SMF8.5A	SMF8.5CA	KT	FT	8.5	9.44	10.4	1.0	10	14.4	13.9
SMF9.0A	SMF9.0CA	KV	FV	9.0	10.0	11.1	1.0	5.0	15.4	13.0
SMF10A	SMF10CA	КX	FX	10	11.1	12.3	1.0	2.5	17.0	11.8
SMF11A	SMF11CA	KZ	FZ	11	12.2	13.5	1.0	2.5	18.2	11.0
SMF12A	SMF12CA	LE	HE	12	13.3	14.7	1.0	2.5	19.9	10.1
SMF13A	SMF13CA	LG	HG	13	14.4	15.9	1.0	1.0	21.5	9.3
SMF14A	SMF14CA	LK	HK	14	15.6	17.2	1.0	1.0	23.2	8.6
SMF15A	SMF15CA	LM	HM	15	16.7	18.5	1.0	1.0	24.4	8.2
SMF16A	SMF16CA	LP	HP	16	17.8	19.7	1.0	1.0	26.0	7.7
SMF17A	SMF17CA	LR	HR	17	18.9	20.9	1.0	1.0	27.6	7.2
SMF18A	SMF18CA	LT	HT	18	20.0	22.1	1.0	1.0	29.2	6.8
SMF20A	SMF20CA	LV	HV	20	22.2	24.5	1.0	1.0	32.4	6.2
SMF22A	SMF22CA	LX	HX	22	24.4	26.9	1.0	1.0	35.5	5.6
SMF24A	SMF24CA	LZ	HZ	24	26.7	29.5	1.0	1.0	38.9	5.1
SMF26A	SMF26CA	ME	JE	26	28.9	31.9	1.0	1.0	42.1	48
SMF28A	SMF28CA	MG	JG	28	31.1	34.4	1.0	1.0	45.4	4.4
SMF30A	SMF30CA	IVIK	JK	30	33.3	36.8	1.0	1.0	48.4	4.1
SMF33A	SMF33CA		JM	33	36.7	40.6	1.0	1.0	53.3	3.8
SMF36A	SMF36CA		JP	30	40.0	44.2	1.0	1.0	58.1	3.4
SMF40A	SMF40CA			40	44.4	49.1	1.0	1.0	60.4	3.1
SMF43A	SMF43CA			43	47.0	55.3	1.0	1.0	09.4 72.7	2.9
SME48A	SMF45CA	MY	3V IV	40	52.2	59.0	1.0	1.0	77.4	2.0
SMI 40A	SMF40CA	MZ	JA 17	40 51	55.5	50.9 62.7	1.0	1.0	92.4	2.0
SMF51A	SME5/CA			54	60.0	66.3	1.0	1.0	87.1	2.4
SME58A	SME58CA	NG	XG	58	64.4	71.2	1.0	1.0	93.6	2.0
SMF60A	SMF60CA	NK	ХК	60	66.7	73.7	1.0	1.0	96.8	1.8
SMF64A	SMF64CA	NM	XM	64	71 1	78.6	1.0	1.0	103	1.0
SMF70A	SMF70CA	NP	XP	70	77.8	86.0	10	1.0	113	1.5
SMF75A	SMF75CA	NR	XR	75	83.3	92.1	1.0	1.0	121	1.4
SMF78A	SMF78CA	NT	ХТ	78	86.7	95.8	1.0	1.0	126	1.4
SMF85A	SMF85CA	NV	XB	85	94.4	104	1.0	1.0	137	1.3
SMF90A	SMF90CA	NX	XX	90	100	111	1.0	1.0	146	1.2
SMF100A	SMF100CA	NZ	XZ	100	111	123	1.0	1.0	162	1.1
SMF110A	SMF110CA	PE	TE	110	122	135	1.0	1.0	177	1.0
SMF120A	SMF120CA	PG	TG	120	133	147	1.0	1.0	193	0.9
SMF130A	SMF130CA	PK	ТК	130	144	159	1.0	1.0	209	0.8
SMF150A	SMF150CA	PM	ТМ	150	167	185	1.0	1.0	243	0.7
SMF160A	SMF160CA	PP	TP	160	178	197	1.0	1.0	259	0.7
SMF170A	SMF170CA	PR	TR	170	189	209	1.0	1.0	275	0.6





#### Fig.1 Peak Pulse Power Rating Curve

Fig.3 Pulse Waveform



40 20 25 50 75 100 125 150 175 Ta,AMBIENT TEMPERATURE,°C Fig.4 Maximum Non-Repetitive Peak

Fig.2 Forward Current Derating Curve

PEAK PULSE POWER(PPP)OR CURRENT(Ipp) DERATINGIN PERCENTAGE%

100

80

60





# PACKAGEMECHANICALDATA



Dimensions in millimeters

Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters.

2.General tolerance:±0.05mm.

3. The pad layout is for reference purposes only.

### REELSPECIFICATION

P/N	PKG	QTY
SMF5.0A - SMF170CA	SOD-123FL	3000



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